# **SDS1630LF**

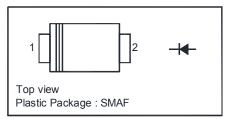
## Surface Mount Schottky Barrier Rectifier Reverse Voltage - 60 V Forward Current - 1 A

### **Features**

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- · Low power loss, high efficiency
- · High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

### **PINNING**

PIN	DESCRIPTION		
1	Cathode		
2	Anode		



### **Maximum Ratings and Electrical Characteristics**

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	Value	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	60	V
Maximum RMS Voltage	$V_{RMS}$	42	V
Maximum DC Blocking Voltage	V <sub>DC</sub> 60		V
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	1	Α
Peak Forward Surge Current 8.3 ms Half Sine-wave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	30	А
Maximum Instantaneous Forward Voltage at 1 A	V <sub>F</sub>	0.5	V
Maximum DC Reverse Current at $T_J = 25^{\circ}$ C Rated DC Blocking Voltage $T_J = 100^{\circ}$ C	I <sub>R</sub>	0.2 5	mA
Typical Junction Capacitance 1)	C <sub>j</sub>	50	pF
Typical Thermal Resistance, Junction to Ambient <sup>2)</sup>	$R_{\theta JA}$	85	°C/W
Operating Junction Temperature Range	T <sub>j</sub>	- 55 to + 125	°C
Storage Temperature Range	T <sub>stg</sub>	- 55 to + 150	°C

<sup>1)</sup> Measured at 1MHz and applied reverse voltage of 4 V D.C.



 $<sup>^{2)}</sup>$  P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

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### **Electrical Characteristics Curves**

Fig 1. Reverse Characteristics Curve

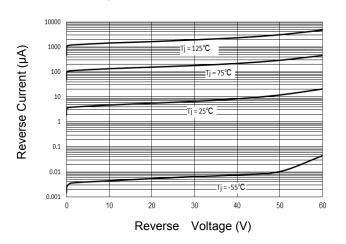


Fig 2. Forward Characteristics Curve

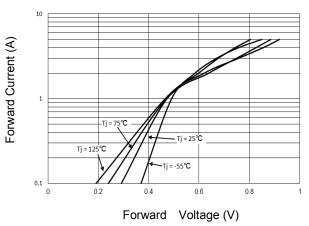


Fig 3. Junction Capacitance

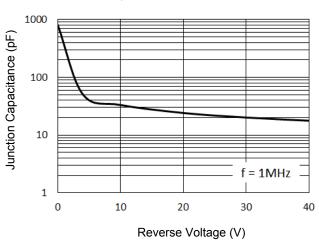
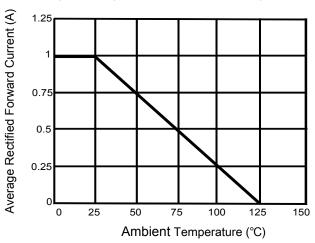
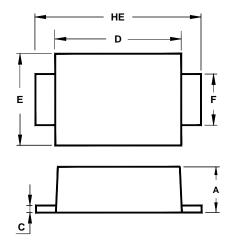


Fig 4. Average Forward Current Derating Curve



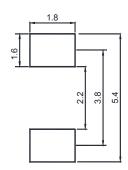
## Package Outline Dimensions (Units: mm)

**SMAF** 



UNIT	Α	С	D	E	F	H <sub>E</sub>
mm	1.1	0.2	3.7	2.80	1.6	4.9
	0.9	0.12	3.3	2.40	1.3	4.4

## **Recommended Soldering Footprint**



Packing information

a detailing in the initiation						
Package	Tape Width (mm)	Pitch		Reel Size		
		mm	inch	mm	inch	Per Reel Packing Quantity
SMAF 12	4 ± 0.1	(0.157 ± 0.004)	178	7	3,000	
			330	13	10,000	

### **Marking information**

" SSL16 " = Part No.

" III " = Cathode line

"YYWW" = Date Code Marking

"Y" = Year

"W" = Week

Font type: Arial



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